

Huawei Ascend 950DT

Da Vinci v3 OAM 2026

OVERVIEW

— FP32 TFLOPS	144 GB VRAM HiZQ 2.0	4.0 TB/s Memory Bandwidth	— TDP
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PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
FP8	1000.0	8	Standard
FP4	2000.0	4	Standard
FP16	500.0	16	Standard
BF16	500.0	16	Standard

MEMORY SPECIFICATIONS

Capacity	144 GB
Type	HiZQ 2.0
Bandwidth	4.0 TB/s
Interface Width	—

POWER & EFFICIENCY

TDP	—
Est. Max Power	—
FP32 Efficiency	—
FP16 Efficiency	—

HARDWARE DETAILS

Vendor: Huawei	Architecture: Da Vinci v3	Process Node: —
Form Factor: OAM	Launch Year: 2026	

INTERCONNECT

GPU-to-GPU: Unified Bus 2.0	Bandwidth: 2.0 TB/s
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